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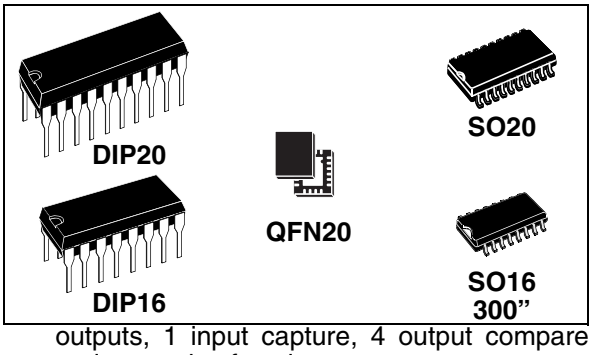
ST7LITE1xB

8-BIT MCU WITH SINGLE VOLTAGE FLASH MEMORY, DATA EEPROM, ADC, 5 TIMERS, SPI

- **Memories**
  - up to 4 Kbytes single voltage extended Flash (XFlash) Program memory with read-out protection, In-Circuit Programming and In-Application programming (ICP and IAP). 10K write/erase cycles guaranteed, data retention: 20 years at 55°C.
  - 256 bytes RAM
  - 128 bytes data EEPROM with read-out protection. 300K write/erase cycles guaranteed, data retention: 20 years at 55°C.
- **Clock, Reset and Supply Management**
  - Enhanced reset system
  - Enhanced low voltage supervisor (LVD) for main supply and an auxiliary voltage detector (AVD) with interrupt capability for implementing safe power-down procedures
  - Clock sources: Internal 1% RC oscillator (on ST7FLITE15B and ST7FLITE19B), crystal/ceramic resonator or external clock
  - Internal 32-MHz input clock for Auto-reload timer
  - Optional x4 or x8 PLL for 4 or 8 MHz internal clock
  - Five Power Saving Modes: Halt, Active-Halt, Auto Wake-up from Halt, Wait and Slow
- **I/O Ports**
  - Up to 17 multifunctional bidirectional I/O lines
  - 7 high sink outputs
- **5 Timers**
  - Configurable watchdog timer
  - Two 8-bit Lite Timers with prescaler, 1 realtime base and 1 input capture
  - Two 12-bit Auto-reload Timers with 4 PWM outputs, 1 input capture, 4 output compare and one pulse functions



- **Communication Interface**
  - SPI synchronous serial interface
- **Interrupt Management**
  - 12 interrupt vectors plus TRAP and RESET
  - 15 external interrupt lines (on 4 vectors)
- **Analog Comparator**
- **A/D Converter**
  - 7 input channels
  - Fixed gain Op-amp
  - 13-bit precision for 0 to 430 mV (@ 5V V_{DD})
  - 10-bit precision for 430 mV to 5V (@ 5V V_{DD})
- **Instruction Set**
  - 8-bit data manipulation
  - 63 basic instructions with illegal opcode detection
  - 17 main addressing modes
  - 8 x 8 unsigned multiply instructions
- **Development Tools**
  - Full hardware/software development package
  - DM (Debug Module)

Device Summary

Features	ST7LITE10B	ST7LITE15B	ST7LITE19B
Program memory - bytes	2K/4K		
RAM (stack) - bytes	256 (128)		
Data EEPROM - bytes	-	-	128
Peripherals	Lite Timer with Wdg, Autoreload Timer, SPI, 10-bit ADC with Op-Amp	Lite Timer with Wdg, Autoreload Timer with 32-MHz input clock, SPI, 10-bit ADC with Op-Amp, Analog Comparator	
Operating Supply	2.7V to 5.5V		
CPU Frequency	Up to 8Mhz(w/ ext OSC at 16MHz)	Up to 8Mhz (w/ ext OSC at 16MHz or int 1MHz RC 1%, PLLx8/4MHz)	
Operating Temperature	-40°C to +85°C / -40°C to +125°C		
Packages	SO20 300”, DIP20, SO16 300”, DIP16	SO20 300”, DIP20, SO16 300”, DIP16, QFN20	

Rev 6

Table of Contents

1 INTRODUCTION 4
2 PIN DESCRIPTION 5
3 REGISTER & MEMORY MAP 9
4 FLASH PROGRAM MEMORY 12
4.1 INTRODUCTION 12
4.2 MAIN FEATURES 12
4.3 PROGRAMMING MODES 12
4.4 ICC INTERFACE 13
4.5 MEMORY PROTECTION 14
4.6 RELATED DOCUMENTATION 14
4.7 REGISTER DESCRIPTION 14
5 DATA EEPROM 15
5.1 INTRODUCTION 15
5.2 MAIN FEATURES 15
5.3 MEMORY ACCESS 16
5.4 POWER SAVING MODES 18
5.5 ACCESS ERROR HANDLING 18
5.6 DATA EEPROM READ-OUT PROTECTION 18
5.7 REGISTER DESCRIPTION 19
6 CENTRAL PROCESSING UNIT 20
6.1 INTRODUCTION 20
6.2 MAIN FEATURES 20
6.3 CPU REGISTERS 20
7 SUPPLY, RESET AND CLOCK MANAGEMENT 23
7.1 INTERNAL RC OSCILLATOR ADJUSTMENT 23
7.2 PHASE LOCKED LOOP 23
7.3 REGISTER DESCRIPTION 25
7.4 MULTI-OSCILLATOR (MO) 27
7.5 RESET SEQUENCE MANAGER (RSM) 28
7.6 SYSTEM INTEGRITY MANAGEMENT (SI) 31
8 INTERRUPTS 36
8.1 NON MASKABLE SOFTWARE INTERRUPT 36
8.2 EXTERNAL INTERRUPTS 36
8.3 PERIPHERAL INTERRUPTS 36
9 POWER SAVING MODES 40
9.1 INTRODUCTION 40
9.2 SLOW MODE 40
9.3 WAIT MODE 41
9.4 HALT MODE 42
9.5 ACTIVE-HALT MODE 43
9.6 AUTO WAKE UP FROM HALT MODE 44
10 I/O PORTS 48
10.1 INTRODUCTION 48
10.2 FUNCTIONAL DESCRIPTION 48
10.3 I/O PORT IMPLEMENTATION 52

Table of Contents

10.4 UNUSED I/O PINS 52
10.5 LOW POWER MODES 52
10.6 INTERRUPTS 52
10.7 DEVICE-SPECIFIC I/O PORT CONFIGURATION 53
10.8 MULTIPLEXED INPUT/OUTPUT PORTS 54
11 ON-CHIP PERIPHERALS 55
11.1 WATCHDOG TIMER (WDG) 55
11.2 DUAL 12-BIT AUTORELOAD TIMER 4 (AT4) 57
11.3 LITE TIMER 2 (LT2) 79
11.4 SERIAL PERIPHERAL INTERFACE (SPI) 84
11.5 10-BIT A/D CONVERTER (ADC) 96
11.6 ANALOG COMPARATOR (CMP) 100
12 INSTRUCTION SET 104
12.1 ST7 ADDRESSING MODES 104
12.2 INSTRUCTION GROUPS 107
13 ELECTRICAL CHARACTERISTICS 110
13.1 PARAMETER CONDITIONS 110
13.2 ABSOLUTE MAXIMUM RATINGS 111
13.3 OPERATING CONDITIONS 112
13.4 SUPPLY CURRENT CHARACTERISTICS 121
13.5 CLOCK AND TIMING CHARACTERISTICS 124
13.6 MEMORY CHARACTERISTICS 126
13.7 EMC CHARACTERISTICS 127
13.8 I/O PORT PIN CHARACTERISTICS 129
13.9 CONTROL PIN CHARACTERISTICS 135
13.10 COMMUNICATION INTERFACE CHARACTERISTICS 137
13.11 10-BIT ADC CHARACTERISTICS 139
13.12 ANALOG COMPARATOR CHARACTERISTICS 143
13.13 PROGRAMMABLE INTERNAL VOLTAGE REFERENCE CHARACTERISTICS 143
13.14 CURRENT BIAS CHARACTERISTICS (FOR COMPARATOR AND INTERNAL VOLTAGE REFERENCE) 143
14 PACKAGE CHARACTERISTICS 144
14.1 PACKAGE MECHANICAL DATA 144
14.2 SOLDERING INFORMATION 148
15 DEVICE CONFIGURATION AND ORDERING INFORMATION 149
15.1 OPTION BYTES 149
15.2 DEVICE ORDERING INFORMATION 151
15.3 DEVELOPMENT TOOLS 153
15.4 ST7 APPLICATION NOTES 154
16 REVISION HISTORY 157

1 INTRODUCTION

The ST7LITE1xB is a member of the ST7 microcontroller family. All ST7 devices are based on a common industry-standard 8-bit core, featuring an enhanced instruction set.

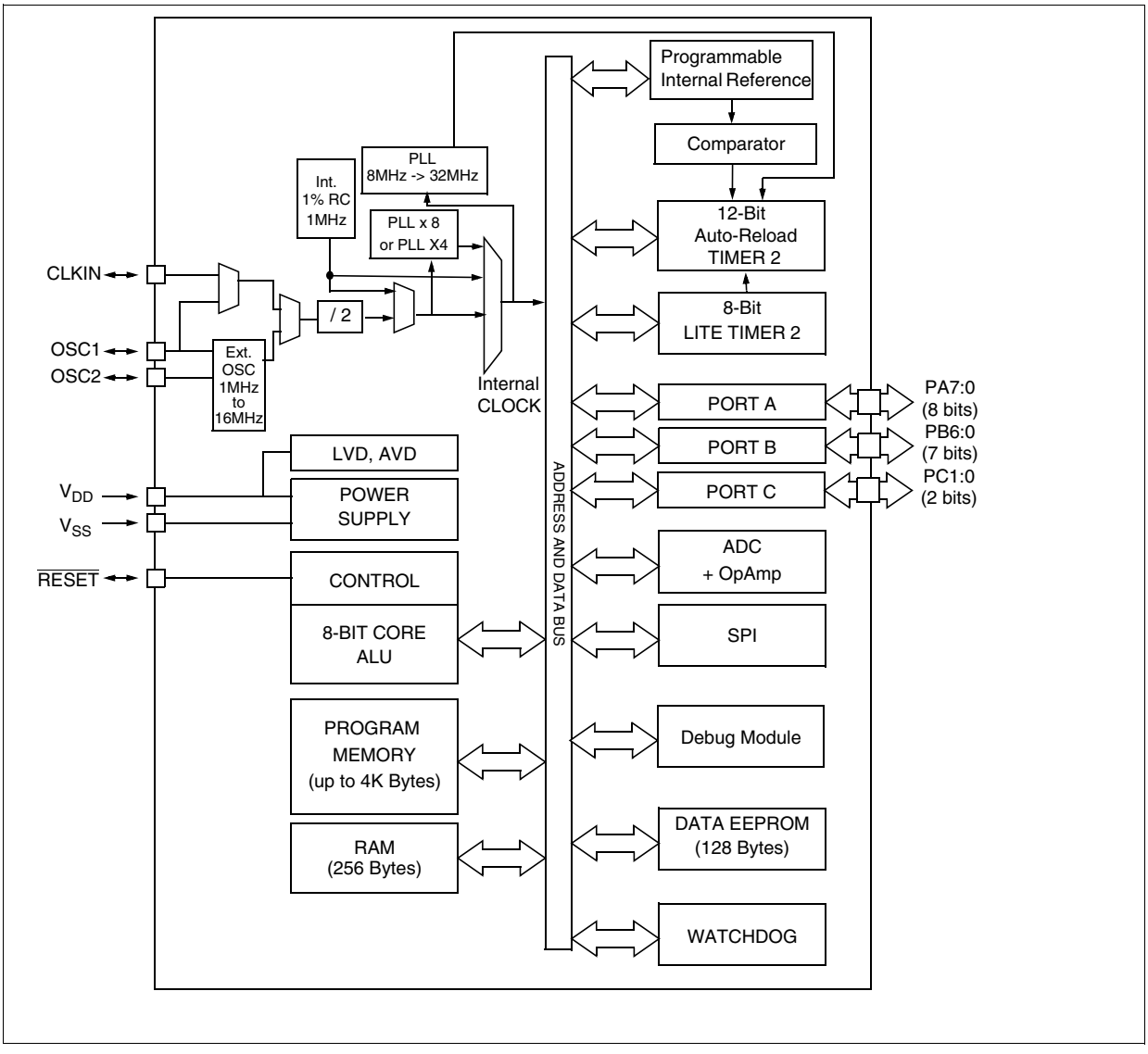
The ST7LITE1xB features FLASH memory with byte-by-byte In-Circuit Programming (ICP) and In-Application Programming (IAP) capability.

Under software control, the ST7LITE1xB device can be placed in WAIT, SLOW, or HALT mode, reducing power consumption when the application is in idle or standby state.

The enhanced instruction set and addressing modes of the ST7 offer both power and flexibility to software developers, enabling the design of highly efficient and compact application code. In addition to standard 8-bit data management, all ST7 microcontrollers feature true bit manipulation, 8x8 unsigned multiplication and indirect addressing modes.

For easy reference, all parametric data are located in section 13 on page 110. The ST7LITE1xB features an on-chip Debug Module (DM) to support In-Circuit Debugging (ICD). For a description of the DM registers, refer to the ST7 ICC Protocol Reference Manual.

Figure 1. General Block Diagram



2 PIN DESCRIPTION

Figure 2. 20-Pin SO and DIP Package Pinout

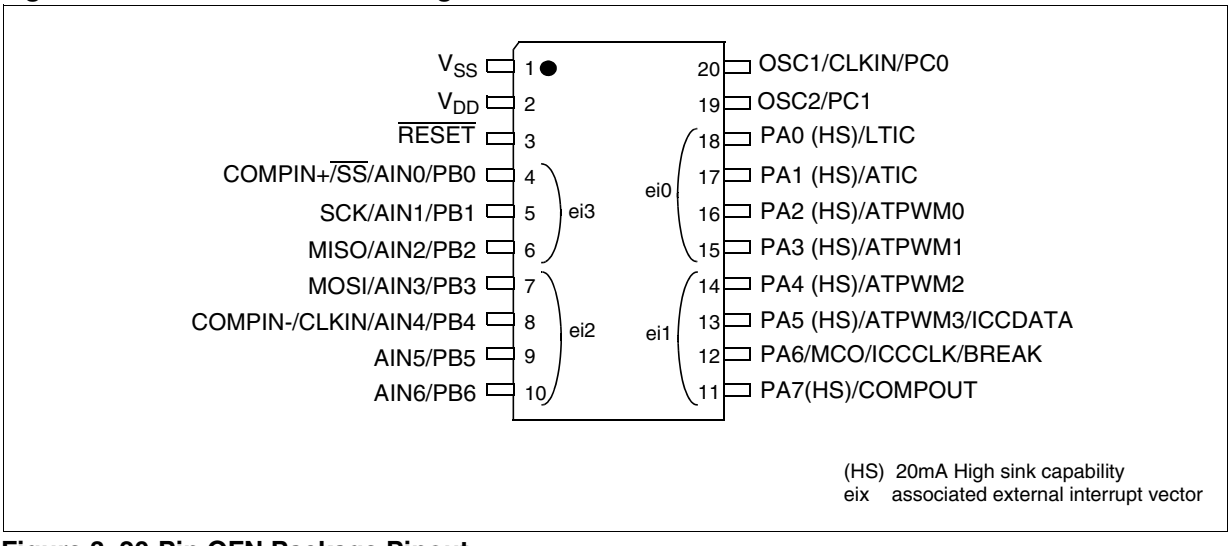
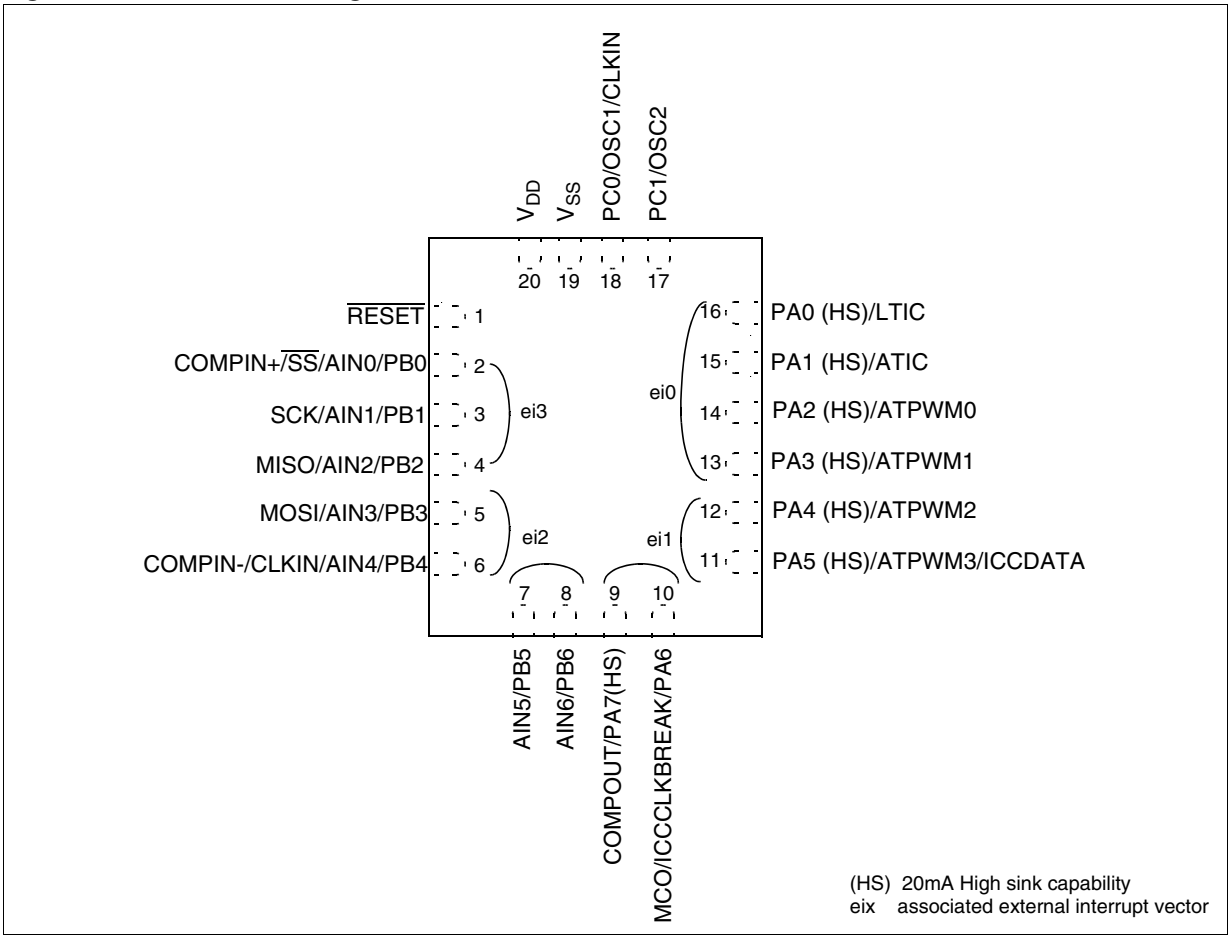
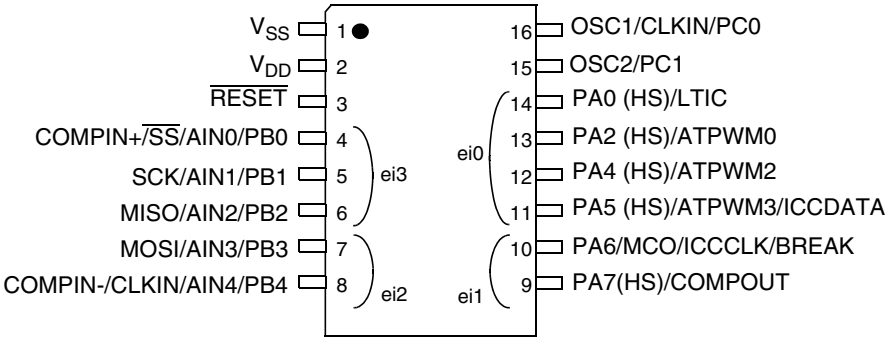


Figure 3. 20-Pin QFN Package Pinout



PIN DESCRIPTION (Cont'd)

Figure 4. 16-Pin SO and DIP Package Pinout



(HS) 20mA high sink capability
eix associated external interrupt vector

PIN DESCRIPTION (Cont'd)

Legend / Abbreviations for Table 1:

Type: I = input, O = output, S = supply

In/Output level: C_T= CMOS $0.3V_{DD}/0.7V_{DD}$ with input trigger

Output level: HS = 20mA high sink (on N-buffer only)

Port and control configuration:

– Input: float = floating, wpu = weak pull-up, int = interrupt, ana = analog

– Output: OD = open drain, PP = push-pull

The RESET configuration of each pin is shown in bold which is valid as long as the device is in reset state.

Table 1. Device Pin Description

Pin No.			Pin Name	Type	Level		Port / Control						Main Function (after reset)	Alternate Function
							Input				Output			
SO20/DPI20	QFN20	SO16/DIP16			Input	Output	float	wpu	int	ana	OD	PP		
1	19	1	V_{SS} [1]	S									Ground	
2	20	2	V_{DD} [1]	S									Main power supply	
3	1	3	$\overline{RESET}$	I/O	C_T			**X**			X		Top priority non maskable interrupt (active low)	
4	2	4	PB0/COMPIN+/ AIN0/$\overline{SS}$	I/O	C_T		**X**	ei3		X	X	X	**Port B0**	ADC Analog Input 0 [2] or SPI Slave Select (active low) or Analog Comparator Input **Caution:** No negative current injection allowed on this pin.
5	3	5	PB1/AIN1/SCK	I/O	C_T		**X**			X	X	X	**Port B1**	ADC Analog Input 1 [2] or SPI Serial Clock
6	4	6	PB2/AIN2/MISO	I/O	C_T		**X**			X	X	X	**Port B2**	ADC Analog Input 2 [2] or SPI Master In/ Slave Out Data
7	5	7	PB3/AIN3/MOSI	I/O	C_T		**X**	ei2		X	X	X	**Port B3**	ADC Analog Input 3 [2] or SPI Master Out / Slave In Data
8	6	8	PB4/AIN4/CLKIN/ COMPIN-	I/O	C_T		**X**			X	X	X	**Port B4**	ADC Analog Input 4 [2] or External clock input or Analog Comparator External Reference Input
9	7	-	PB5/AIN5	I/O	C_T		**X**			X	X	X	**Port B5**	ADC Analog Input 5 [2]
10	8	-	PB6/AIN6	I/O	C_T		**X**			X	X	X	**Port B6**	ADC Analog Input 6 [2]
11	9	9	PA7/COMPOUT	I/O	C_T	HS	**X**	ei1			X	X	**Port A7**	Analog Comparator Output

Pin No.			Pin Name	Type	Level		Port / Control						Main Function (after reset)	Alternate Function
							Input				Output			
SO20/DPI20	QFN20	SO16/DIP16			Input	Output	float	wpu	int	ana	OD	PP		
12	10	10	PA6 /MCO/ ICCCLK/BREAK	I/O	C_T		X	**ei1**			X	X	**Port A6**	Main Clock Output or In Circuit Communication Clock or External BREAK **Caution:** During normal operation this pin must be pulled- up, internally or externally (external pull-up of 10k mandatory in noisy environment). This is to avoid entering ICC mode unexpectedly during a reset. In the application, even if the pin is configured as output, any reset will put it back in input pull-up
13	11	11	PA5 /ICCDATA/ ATPWM3	I/O	C_T	HS	**X**	ei1			X	X	**Port A5**	In Circuit Communication Data or Auto-Reload Timer PWM3
14	12	12	PA4/ATPWM2	I/O	C_T	HS	**X**				X	X	**Port A4**	Auto-Reload Timer PWM2
15	13	-	PA3/ATPWM1	I/O	C_T	HS	**X**	ei0			X	X	**Port A3**	Auto-Reload Timer PWM1
16	14	13	PA2/ATPWM0	I/O	C_T	HS	**X**				X	X	**Port A2**	Auto-Reload Timer PWM0
17	15	-	PA1/ATIC	I/O	C_T	HS	**X**				X	X	**Port A1**	Auto-Reload Timer Input Capture
18	16	14	PA0/LTIC	I/O	C_T	HS	**X**				X	X	**Port A0**	Lite Timer Input Capture
19	17	15	OSC2/PC1	I/O			**X**					X	**Port C1**[3)]	Resonator oscillator inverter output
20	18	16	OSC1/CLKIN/PC0	I/O			**X**					X	**Port C0**[3)]	Resonator oscillator inverter input or External clock input

Notes:

1. It is mandatory to connect all available V_{DD} and V_{DDA} pins to the supply voltage and all V_{SS} and V_{SSA} pins to ground.

2. When the pin is configured as analog input, positive and negative current injections are not allowed.

3. PCOR not implemented but p-transistor always active in output mode (refer to Figure 32 on page 50).

3 REGISTER & MEMORY MAP

As shown in Figure 5, the MCU is capable of addressing 64K bytes of memories and I/O registers.

The available memory locations consist of 128 bytes of register locations, 256 bytes of RAM, 128 bytes of data EEPROM and up to 4 Kbytes of flash program memory. The RAM space includes up to 128 bytes for the stack from 180h to 1FFh.

The highest address bytes contain the user reset and interrupt vectors.

The Flash memory contains two sectors (see Figure 5) mapped in the upper part of the ST7 addressing space so the reset and interrupt vectors are located in Sector 0 (F000h-FFFFh).

The size of Flash Sector 0 and other device options are configurable by Option byte (refer to section 15.1 on page 149).

IMPORTANT: Memory locations marked as "Reserved" must never be accessed. Accessing a reserved area can have unpredictable effects on the device.

Figure 5. Memory Map

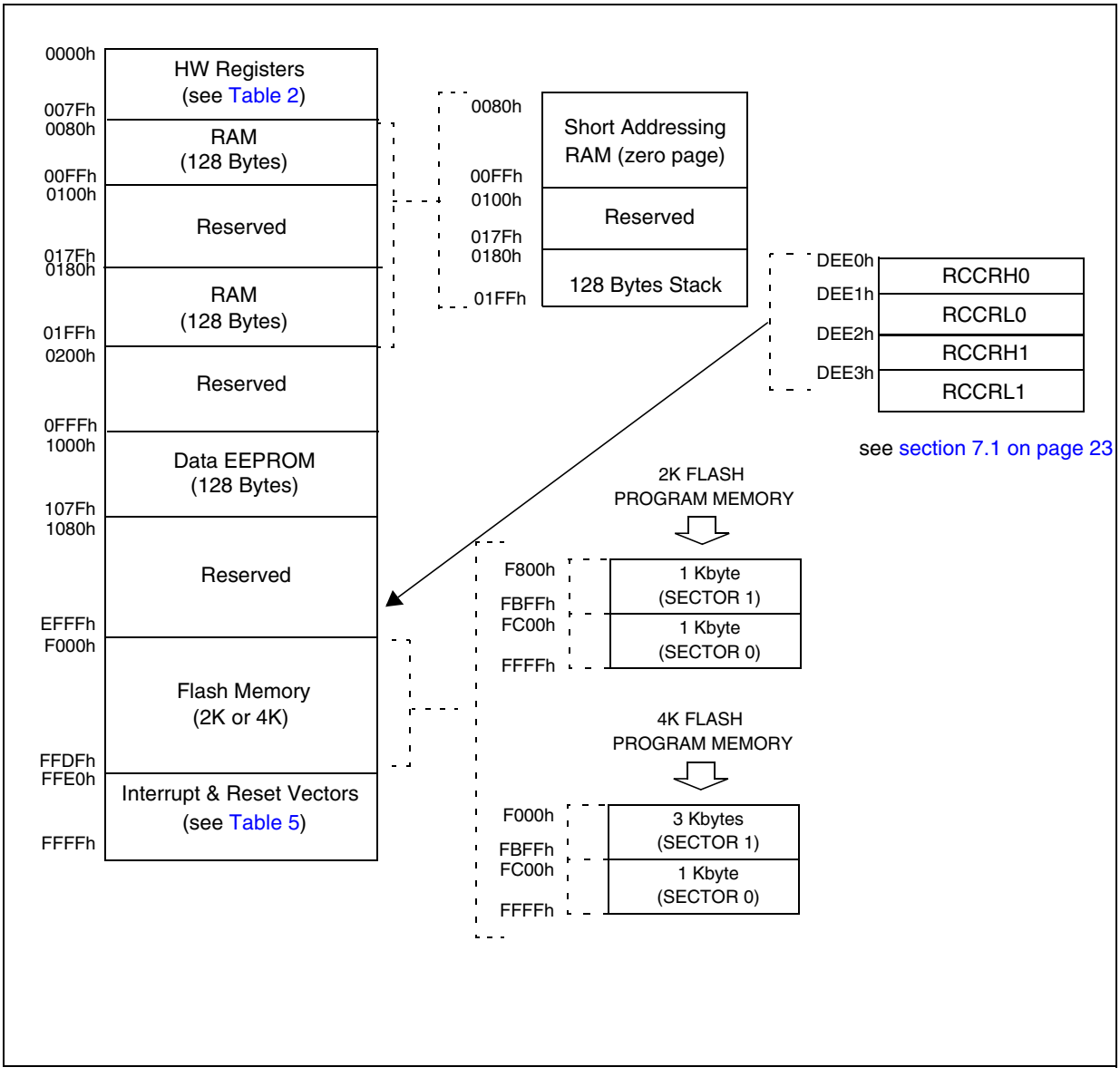


Table 2. Hardware Register Map

Address	Block	Register Label	Register Name	Reset Status	Remarks
0000h	Port A	PADR	Port A Data Register	FFh[1)]	R/W
0001h		PADDR	Port A Data Direction Register	00h	R/W
0002h		PAOR	Port A Option Register	40h	R/W
0003h	Port B	PBDR	Port B Data Register	FFh [1)]	R/W
0004h		PBDDR	Port B Data Direction Register	00h	R/W
0005h		PBOR	Port B Option Register	00h	R/W[2)]
0006h	Port C	PCDR	Port C Data Register	0xh	R/W
0007h		PCDDR	Port C Data Direction Register	00h	R/W
0008h	LITE TIMER 2	LTCSR2	Lite Timer Control/Status Register 2	00h	R/W
0009h		LTARR	Lite Timer Auto-reload Register	00h	R/W
000Ah		LTCNTR	Lite Timer Counter Register	00h	Read Only
000Bh		LTCSR1	Lite Timer Control/Status Register 1	0X00 0000b	R/W
000Ch		LTICR	Lite Timer Input Capture Register	00h	Read Only
000Dh	AUTO-RELOAD TIMER 2	ATCSR	Timer Control/Status Register	0X00 0000b	R/W
000Eh		CNTRH	Counter Register High	00h	Read Only
000Fh		CNTRL	Counter Register Low	00h	Read Only
0010h		ATRH	Auto-Reload Register High	00h	R/W
0011h		ATRL	Auto-Reload Register Low	00h	R/W
0012h		PWMCR	PWM Output Control Register	00h	R/W
0013h		PWM0CSR	PWM 0 Control/Status Register	00h	R/W
0014h		PWM1CSR	PWM 1 Control/Status Register	00h	R/W
0015h		PWM2CSR	PWM 2 Control/Status Register	00h	R/W
0016h		PWM3CSR	PWM 3 Control/Status Register	00h	R/W
0017h		DCR0H	PWM 0 Duty Cycle Register High	00h	R/W
0018h		DCR0L	PWM 0 Duty Cycle Register Low	00h	R/W
0019h		DCR1H	PWM 1 Duty Cycle Register High	00h	R/W
001Ah		DCR1L	PWM 1 Duty Cycle Register Low	00h	R/W
001Bh		DCR2H	PWM 2 Duty Cycle Register High	00h	R/W
001Ch		DCR2L	PWM 2 Duty Cycle Register Low	00h	R/W
001Dh		DCR3H	PWM 3 Duty Cycle Register High	00h	R/W
001Eh		DCR3L	PWM 3 Duty Cycle Register Low	00h	R/W
001Fh		ATICRH	Input Capture Register High	00h	Read Only
0020h		ATICRL	Input Capture Register Low	00h	Read Only
0021h		ATCSR2	Timer Control/Status Register 2	03h	R/W
0022h		BREAKCR	Break Control Register	00h	R/W
0023h		ATR2H	Auto-Reload Register 2 High	00h	R/W
0024h		ATR2L	Auto-Reload Register 2 Low	00h	R/W
0025h		DTGR	Dead Time Generation Register	00h	R/W
0026h		BREAKEN	Break Enable Register	03h	R/W
0027h to 002Bh	Reserved area (5 bytes)				
002Ch	Comparator Voltage Reference	VREFCR	Internal Voltage Reference Control Register	00h	R/W
002Dh	Comparator	CMPCR	Comparator and Internal Reference Control Register	00h	R/W
002Eh	WDG	WDGCR	Watchdog Control Register	7Fh	R/W

Address	Block	Register Label	Register Name	Reset Status	Remarks
0002Fh	FLASH	FCSR	Flash Control/Status Register	00h	R/W
00030h	EEPROM	EECSR	Data EEPROM Control/Status Register	00h	R/W
0031h 0032h 0033h	SPI	SPIDR SPICR SPICSR	SPI Data I/O Register SPI Control Register SPI Control Status Register	xxh 0xh 00h	R/W R/W R/W
0034h 0035h 0036h	ADC	ADCCSR ADCDRH ADCDRL	A/D Control Status Register A/D Data Register High A/D Amplifier Control/Data Low Register	00h xxh 0xh	R/W Read Only R/W
0037h	ITC	EICR	External Interrupt Control Register	00h	R/W
0038h	MCC	MCCSR	Main Clock Control/Status Register	00h	R/W
0039h 003Ah	Clock and Reset	RCCR SICSR	RC oscillator Control Register System Integrity Control/Status Register	FFh 0110 0xx0b	R/W R/W
003Bh	PLL clock select	PLLTST	PLL test register	00h	R/W
003Ch	ITC	EISR	External Interrupt Selection Register	0Ch	R/W
003Dh to 0048h	Reserved area (12 bytes)				
0049h 004Ah	AWU	AWUPR AWUCSR	AWU Prescaler Register AWU Control/Status Register	FFh 00h	R/W R/W
004Bh 004Ch 004Dh 004Eh 004Fh 0050h 0051h	DM[3]	DMCR DMSR DMBK1H DMBK1L DMBK2H DMBK2L DMCR2	DM Control Register DM Status Register DM Breakpoint Register 1 High DM Breakpoint Register 1 Low DM Breakpoint Register 2 High DM Breakpoint Register 2 Low DM Control Register 2	00h 00h 00h 00h 00h 00h 00h	R/W R/W R/W R/W R/W R/W R/W
0052h to 007Fh	Reserved area (46 bytes)				

Legend: x=undefined, R/W=read/write

Notes:

1. The contents of the I/O port DR registers are readable only in output configuration. In input configuration, the values of the I/O pins are returned instead of the DR register contents.

2. The bits associated with unavailable pins must always keep their reset value.

3. For a description of the Debug Module registers, see ICC protocol reference manual.

4 FLASH PROGRAM MEMORY

4.1 Introduction

The ST7 single voltage extended Flash (XFlash) is a non-volatile memory that can be electrically erased and programmed either on a byte-by-byte basis or up to 32 bytes in parallel.

The XFlash devices can be programmed off-board (plugged in a programming tool) or on-board using In-Circuit Programming or In-Application Programming.

The array matrix organisation allows each sector to be erased and reprogrammed without affecting other sectors.

4.2 Main Features

- ICP (In-Circuit Programming)
- IAP (In-Application Programming)
- ICT (In-Circuit Testing) for downloading and executing user application test patterns in RAM
- Sector 0 size configurable by option byte
- Read-out and write protection

4.3 PROGRAMMING MODES

The ST7 can be programmed in three different ways:

– Insertion in a programming tool. In this mode, FLASH sectors 0 and 1, option byte row and data EEPROM (if present) can be programmed or erased.

– In-Circuit Programming. In this mode, FLASH sectors 0 and 1, option byte row and data EEPROM (if present) can be programmed or erased without removing the device from the application board.

– In-Application Programming. In this mode, sector 1 and data EEPROM (if present) can be programmed or erased without removing the device from the application board and while the application is running.

4.3.1 In-Circuit Programming (ICP)

ICP uses a protocol called ICC (In-Circuit Communication) which allows an ST7 plugged on a printed circuit board (PCB) to communicate with an external programming device connected via cable. ICP is performed in three steps:

Switch the ST7 to ICC mode (In-Circuit Communications). This is done by driving a specific signal sequence on the ICCCLK/DATA pins while the RESET pin is pulled low. When the ST7 enters ICC mode, it fetches a specific RESET vector which points to the ST7 System Memory containing the ICC protocol routine. This routine enables the ST7 to receive bytes from the ICC interface.

– Download ICP Driver code in RAM from the ICCDATA pin

– Execute ICP Driver code in RAM to program the FLASH memory

Depending on the ICP Driver code downloaded in RAM, FLASH memory programming can be fully customized (number of bytes to program, program locations, or selection of the serial communication interface for downloading).

4.3.2 In Application Programming (IAP)

This mode uses an IAP Driver program previously programmed in Sector 0 by the user (in ICP mode).

This mode is fully controlled by user software. This allows it to be adapted to the user application, (user-defined strategy for entering programming mode, choice of communications protocol used to fetch the data to be stored etc.)
IAP mode can be used to program any memory areas except Sector 0, which is write/erase protected to allow recovery in case errors occur during the programming operation.

FLASH PROGRAM MEMORY (Cont'd)

4.4 ICC interface

ICP needs a minimum of 4 and up to 6 pins to be connected to the programming tool. These pins are:

- $\overline{\text{RESET}}$: device reset
- V_{SS}: device power supply ground
- ICCCLK: ICC output serial clock pin
- ICCDATA: ICC input serial data pin
- OSC1: main clock input for external source (not required on devices without OSC1/OSC2 pins)
- V_{DD}: application board power supply (optional, see Note 3)

Notes:

1. If the ICCCLK or ICCDATA pins are only used as outputs in the application, no signal isolation is necessary. As soon as the Programming Tool is plugged to the board, even if an ICC session is not in progress, the ICCCLK and ICCDATA pins are not available for the application. If they are used as inputs by the application, isolation such as a serial resistor has to be implemented in case another device forces the signal. Refer to the Programming Tool documentation for recommended resistor values.

2. During the ICP session, the programming tool must control the $\overline{\text{RESET}}$ pin. This can lead to conflicts between the programming tool and the application reset circuit if it drives more than 5mA at high level (push pull output or pull-up resistor<1K). A schottky diode can be used to isolate the application RESET circuit in this case. When using a classical RC network with R>1K or a reset management IC with open drain output and pull-up resistor>1K, no additional components are needed. In all cases the user must ensure that no external reset is generated by the application during the ICC session.

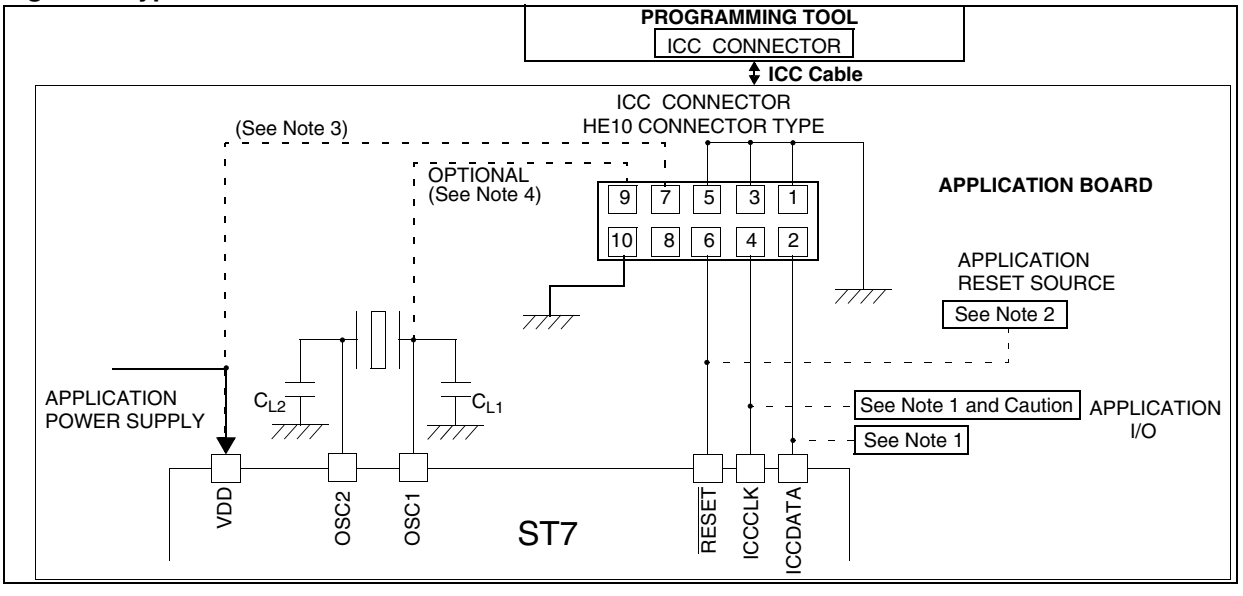
3. The use of pin 7 of the ICC connector depends on the Programming Tool architecture. This pin must be connected when using most ST Programming Tools (it is used to monitor the application power supply). Please refer to the Programming Tool manual.

4. Pin 9 has to be connected to the OSC1 pin of the ST7 when the clock is not available in the application or if the selected clock option is not programmed in the option byte. ST7 devices with multi-oscillator capability need to have OSC2 grounded in this case.

5. In 38-pulse ICC mode, the internal RC oscillator is forced as a clock source, regardless of the selection in the option byte. For ST7LITE10B devices which do not support the internal RC oscillator, the "option byte disabled" mode must be used (35-pulse ICC mode entry, clock provided by the tool).

Caution: During normal operation the ICCCLK pin must be pulled- up, internally or externally (external pull-up of 10k mandatory in noisy environment). This is to avoid entering ICC mode unexpectedly during a reset. In the application, even if the pin is configured as output, any reset will put it back in input pull-up.

Figure 6. Typical ICC Interface



FLASH PROGRAM MEMORY (Cont'd)

4.5 Memory Protection

There are two different types of memory protection: Read Out Protection and Write/Erase Protection which can be applied individually.

4.5.1 Read out Protection

Readout protection, when selected provides a protection against program memory content extraction and against write access to Flash memory. Even if no protection can be considered as totally unbreakable, the feature provides a very high level of protection for a general purpose microcontroller. Both program and data E^2 memory are protected.

In flash devices, this protection is removed by reprogramming the option. In this case, both program and data E^2 memory are automatically erased and the device can be reprogrammed.

Read-out protection selection depends on the device type:

– In Flash devices it is enabled and removed through the FMP_R bit in the option byte.

– In ROM devices it is enabled by mask option specified in the Option List.

4.5.2 Flash Write/Erase Protection

Write/erase protection, when set, makes it impossible to both overwrite and erase program memory. It does not apply to E^2 data. Its purpose is to provide advanced security to applications and prevent any change being made to the memory content.

Warning: Once set, Write/erase protection can never be removed. A write-protected flash device is no longer reprogrammable.

Write/erase protection is enabled through the FMP_W bit in the option byte.

4.6 Related Documentation

For details on Flash programming and ICC protocol, refer to the ST7 Flash Programming Reference Manual and to the ST7 ICC Protocol Reference Manual.

4.7 Register Description

FLASH CONTROL/STATUS REGISTER (FCSR)
Read/Write
Reset Value: 000 0000 (00h)
1st RASS Key: 0101 0110 (56h)
2nd RASS Key: 1010 1110 (AEh)

7							0
0	0	0	0	0	OPT	LAT	PGM

Note: This register is reserved for programming using ICP, IAP or other programming methods. It controls the XFlash programming and erasing operations.

When an EPB or another programming tool is used (in socket or ICP mode), the RASS keys are sent automatically.

5 DATA EEPROM

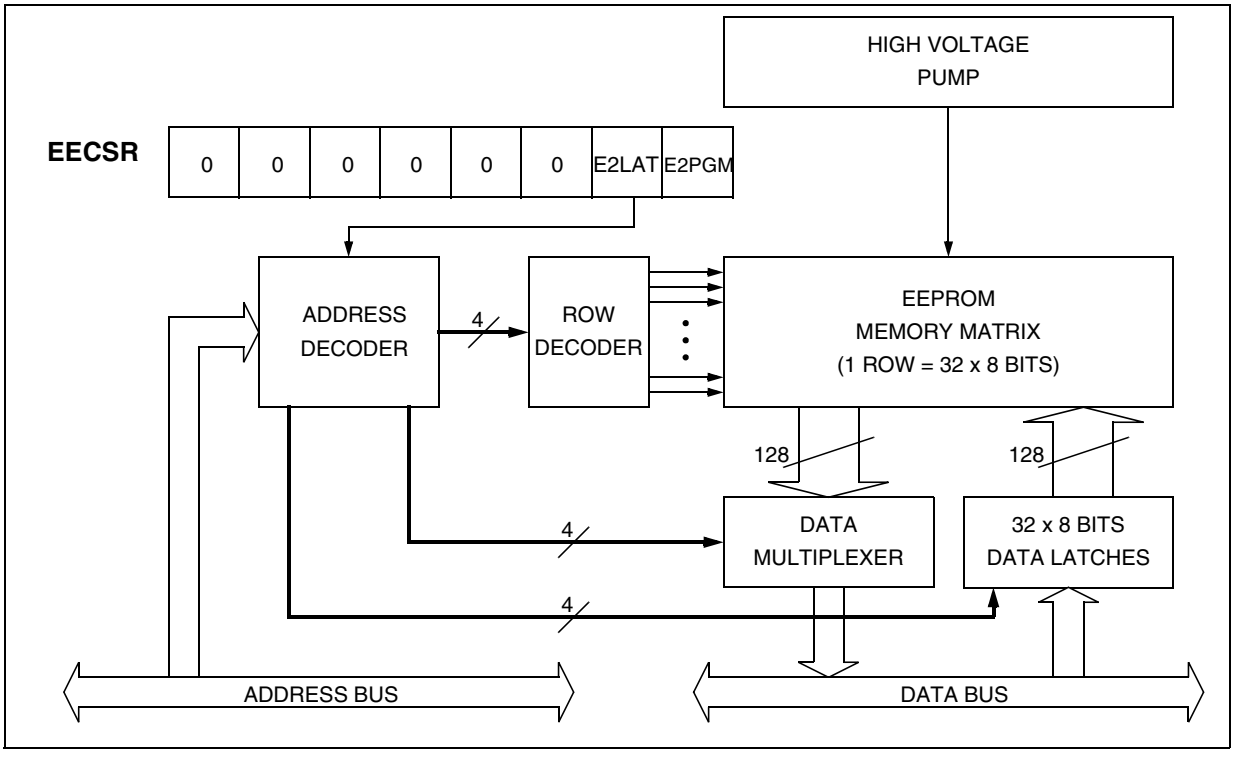
5.1 INTRODUCTION

The Electrically Erasable Programmable Read Only Memory can be used as a non volatile back-up for storing data. Using the EEPROM requires a basic access protocol described in this chapter.

5.2 MAIN FEATURES

- Up to 32 Bytes programmed in the same cycle
- EEPROM mono-voltage (charge pump)
- Chained erase and programming cycles
- Internal control of the global programming cycle duration
- WAIT mode management
- Readout protection

Figure 7. EEPROM Block Diagram



DATA EEPROM (Cont'd)

5.3 MEMORY ACCESS

The Data EEPROM memory read/write access modes are controlled by the E2LAT bit of the EEPROM Control/Status register (EECSR). The flowchart in Figure 8 describes these different memory access modes.

Read Operation (E2LAT=0)

The EEPROM can be read as a normal ROM location when the E2LAT bit of the EECSR register is cleared.

On this device, Data EEPROM can also be used to execute machine code. Take care not to write to the Data EEPROM while executing from it. This would result in an unexpected code being executed.

Write Operation (E2LAT=1)

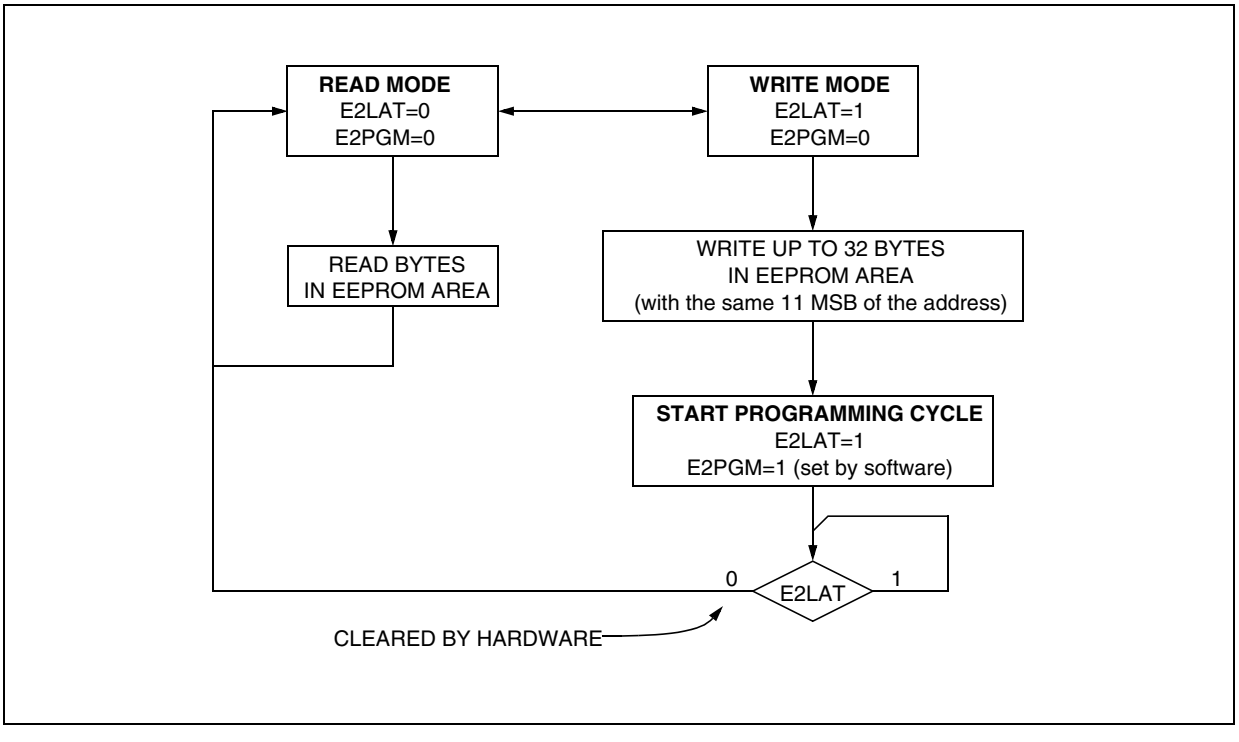
To access the write mode, the E2LAT bit has to be set by software (the E2PGM bit remains cleared). When a write access to the EEPROM area occurs, the value is latched inside the 32 data latches according to its address.

When PGM bit is set by the software, all the previous bytes written in the data latches (up to 32) are programmed in the EEPROM cells. The effective high address (row) is determined by the last EEPROM write sequence. To avoid wrong programming, the user must take care that all the bytes written between two programming sequences have the same high address: only the five Least Significant Bits of the address can change.

At the end of the programming cycle, the PGM and LAT bits are cleared simultaneously.

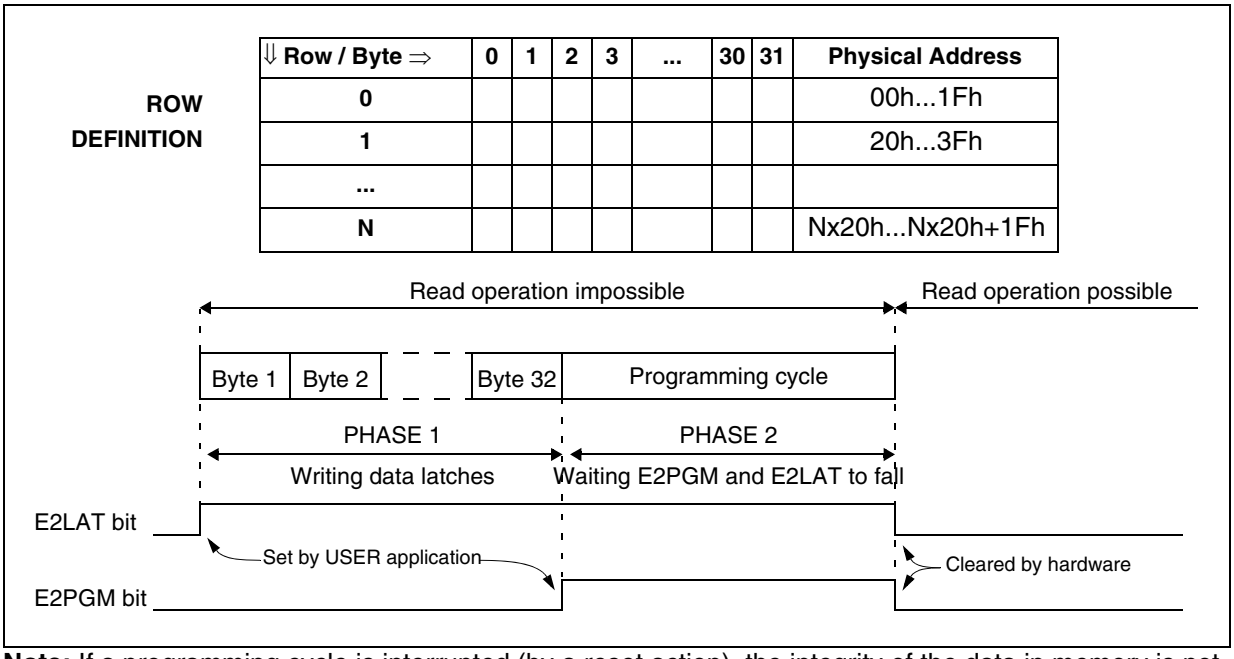
Note: Care should be taken during the programming cycle. Writing to the same memory location will over-program the memory (logical AND between the two write access data result) because the data latches are only cleared at the end of the programming cycle and by the falling edge of the E2LAT bit.
It is not possible to read the latched data.
This note is illustrated by the Figure 10.

Figure 8. Data EEPROM Programming Flowchart



DATA EEPROM (Cont'd)

Figure 9. Data E^2PROM Write Operation



Note: If a programming cycle is interrupted (by a reset action), the integrity of the data in memory is not guaranteed.

DATA EEPROM (Cont'd)

5.4 POWER SAVING MODES

Wait mode

The DATA EEPROM can enter WAIT mode on execution of the WFI instruction of the microcontroller or when the microcontroller enters Active-HALT mode.The DATA EEPROM will immediately enter this mode if there is no programming in progress, otherwise the DATA EEPROM will finish the cycle and then enter WAIT mode.

Active-Halt mode

Refer to Wait mode.

Halt mode

The DATA EEPROM immediately enters HALT mode if the microcontroller executes the HALT instruction. Therefore the EEPROM will stop the function in progress, and data may be corrupted.

5.5 ACCESS ERROR HANDLING

If a read access occurs while E2LAT=1, then the data bus will not be driven.

If a write access occurs while E2LAT=0, then the data on the bus will not be latched.

If a programming cycle is interrupted (by a RESET action), the integrity of the data in memory will not be guaranteed.

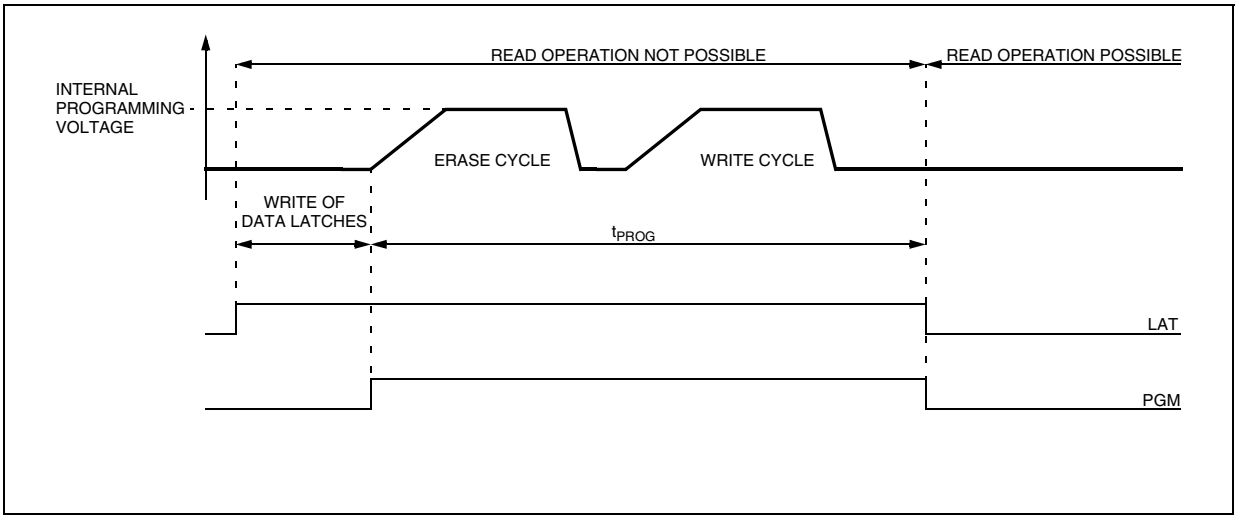
5.6 Data EEPROM Read-out Protection

The read-out protection is enabled through an option bit (see option byte section).

When this option is selected, the programs and data stored in the EEPROM memory are protected against read-out (including a re-write protection). In Flash devices, when this protection is removed by reprogramming the Option Byte, the entire Program memory and EEPROM is first automatically erased.

Note: Both Program Memory and data EEPROM are protected using the same option bit.

Figure 10. Data EEPROM Programming Cycle



DATA EEPROM (Cont'd)

5.7 REGISTER DESCRIPTION

EEPROM CONTROL/STATUS REGISTER (EECSR)

Read/Write

Reset Value: 0000 0000 (00h)

7							0
0	0	0	0	0	0	E2LAT	E2PGM

Bits 7:2 = Reserved, forced by hardware to 0.

Bit 1 = **E2LAT** *Latch Access Transfer*
This bit is set by software. It is cleared by hardware at the end of the programming cycle. It can only be cleared by software if the E2PGM bit is cleared.
0: Read mode
1: Write mode

Bit 0 = **E2PGM** *Programming control and status*
This bit is set by software to begin the programming cycle. At the end of the programming cycle, this bit is cleared by hardware.
0: Programming finished or not yet started
1: Programming cycle is in progress

Note: if the E2PGM bit is cleared during the programming cycle, the memory data is not guaranteed

Table 3. DATA EEPROM Register Map and Reset Values

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
0030h	**EECSR**							E2LAT	E2PGM
	Reset Value	0	0	0	0	0	0	0	0

6 CENTRAL PROCESSING UNIT

6.1 INTRODUCTION

This CPU has a full 8-bit architecture and contains six internal registers allowing efficient 8-bit data manipulation.

6.2 MAIN FEATURES

- 63 basic instructions
- Fast 8-bit by 8-bit multiply
- 17 main addressing modes
- Two 8-bit index registers
- 16-bit stack pointer
- Low power modes
- Maskable hardware interrupts
- Non-maskable software interrupt

6.3 CPU REGISTERS

The six CPU registers shown in Figure 1 are not present in the memory mapping and are accessed by specific instructions.

Accumulator (A)

The Accumulator is an 8-bit general purpose register used to hold operands and the results of the arithmetic and logic calculations and to manipulate data.

Index Registers (X and Y)

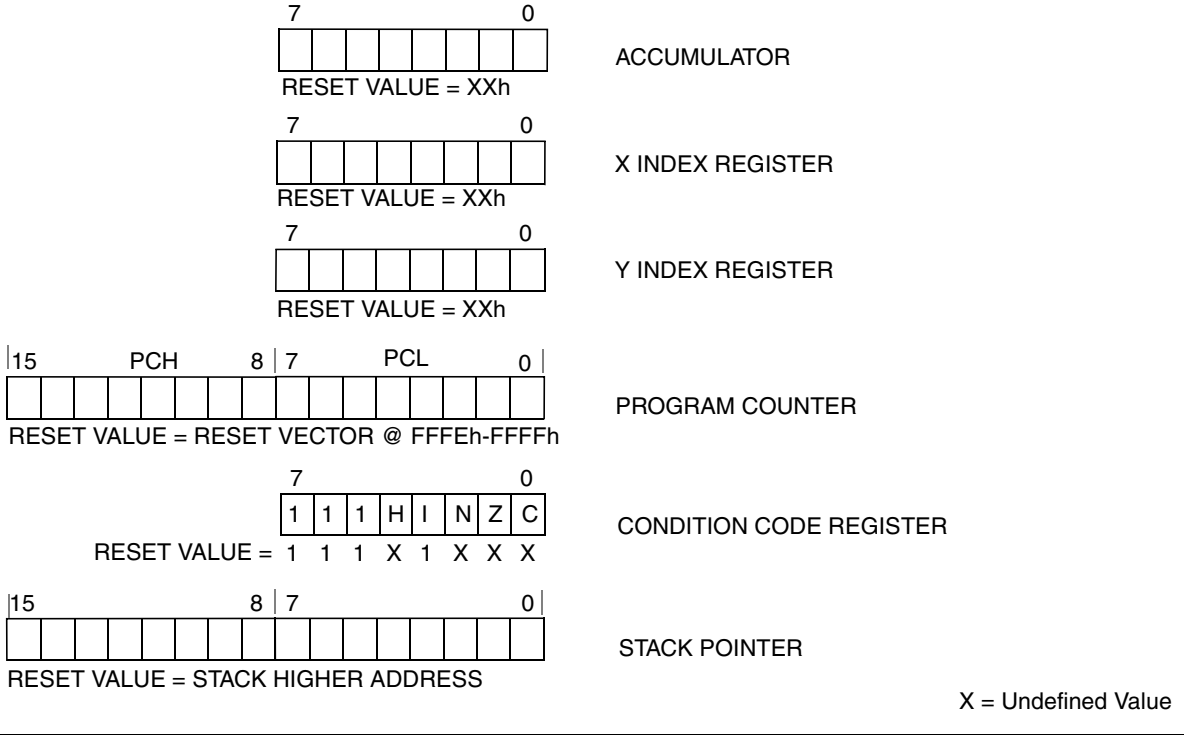
In indexed addressing modes, these 8-bit registers are used to create either effective addresses or temporary storage areas for data manipulation. (The Cross-Assembler generates a precede instruction (PRE) to indicate that the following instruction refers to the Y register.)

The Y register is not affected by the interrupt automatic procedures (not pushed to and popped from the stack).

Program Counter (PC)

The program counter is a 16-bit register containing the address of the next instruction to be executed by the CPU. It is made of two 8-bit registers PCL (Program Counter Low which is the LSB) and PCH (Program Counter High which is the MSB).

Figure 11. CPU Registers



CPU REGISTERS (cont'd)

CONDITION CODE REGISTER (CC)

Read/Write

Reset Value: 111x1xxx

7							0
1	1	1	H	I	N	Z	C

The 8-bit Condition Code register contains the interrupt mask and four flags representative of the result of the instruction just executed. This register can also be handled by the PUSH and POP instructions.

These bits can be individually tested and/or controlled by specific instructions.

Bit 4 = **H** *Half carry*

This bit is set by hardware when a carry occurs between bits 3 and 4 of the ALU during an ADD or ADC instruction. It is reset by hardware during the same instructions.
0: No half carry has occurred.
1: A half carry has occurred.

This bit is tested using the JRH or JRNH instruction. The H bit is useful in BCD arithmetic subroutines.

Bit 3 = **I** *Interrupt mask*

This bit is set by hardware when entering in interrupt or by software to disable all interrupts except the TRAP software interrupt. This bit is cleared by software.
0: Interrupts are enabled.
1: Interrupts are disabled.

This bit is controlled by the RIM, SIM and IRET instructions and is tested by the JRM and JRNM instructions.

Note: Interrupts requested while I is set are latched and can be processed when I is cleared. By default an interrupt routine is not interruptible because the I bit is set by hardware at the start of the routine and reset by the IRET instruction at the end of the routine. If the I bit is cleared by software in the interrupt routine, pending interrupts are serviced regardless of the priority level of the current interrupt routine.

Bit 2 = **N** *Negative*

This bit is set and cleared by hardware. It is representative of the result sign of the last arithmetic, logical or data manipulation. It is a copy of the 7^{th} bit of the result.
0: The result of the last operation is positive or null.
1: The result of the last operation is negative (that is, the most significant bit is a logic 1).

This bit is accessed by the JRMI and JRPL instructions.

Bit 1 = **Z** *Zero*

This bit is set and cleared by hardware. This bit indicates that the result of the last arithmetic, logical or data manipulation is zero.
0: The result of the last operation is different from zero.
1: The result of the last operation is zero.

This bit is accessed by the JREQ and JRNE test instructions.

Bit 0 = **C** *Carry/borrow*

This bit is set and cleared by hardware and software. It indicates an overflow or an underflow has occurred during the last arithmetic operation.
0: No overflow or underflow has occurred.
1: An overflow or underflow has occurred.

This bit is driven by the SCF and RCF instructions and tested by the JRC and JRNC instructions. It is also affected by the "bit test and branch", shift and rotate instructions.

CPU REGISTERS (Cont'd)

STACK POINTER (SP)

Read/Write

Reset Value: 01FFh

15							8
0	0	0	0	0	0	0	1

7							0
1	SP6	SP5	SP4	SP3	SP2	SP1	SP0

The Stack Pointer is a 16-bit register which is always pointing to the next free location in the stack. It is then decremented after data has been pushed onto the stack and incremented before data is popped from the stack (see Figure 12).

Since the stack is 128 bytes deep, the 9 most significant bits are forced by hardware. Following an MCU Reset, or after a Reset Stack Pointer instruction (RSP), the Stack Pointer contains its reset value (the SP6 to SP0 bits are set) which is the stack higher address.

The least significant byte of the Stack Pointer (called S) can be directly accessed by a LD instruction.

Note: When the lower limit is exceeded, the Stack Pointer wraps around to the stack upper limit, without indicating the stack overflow. The previously stored information is then overwritten and therefore lost. The stack also wraps in case of an underflow.

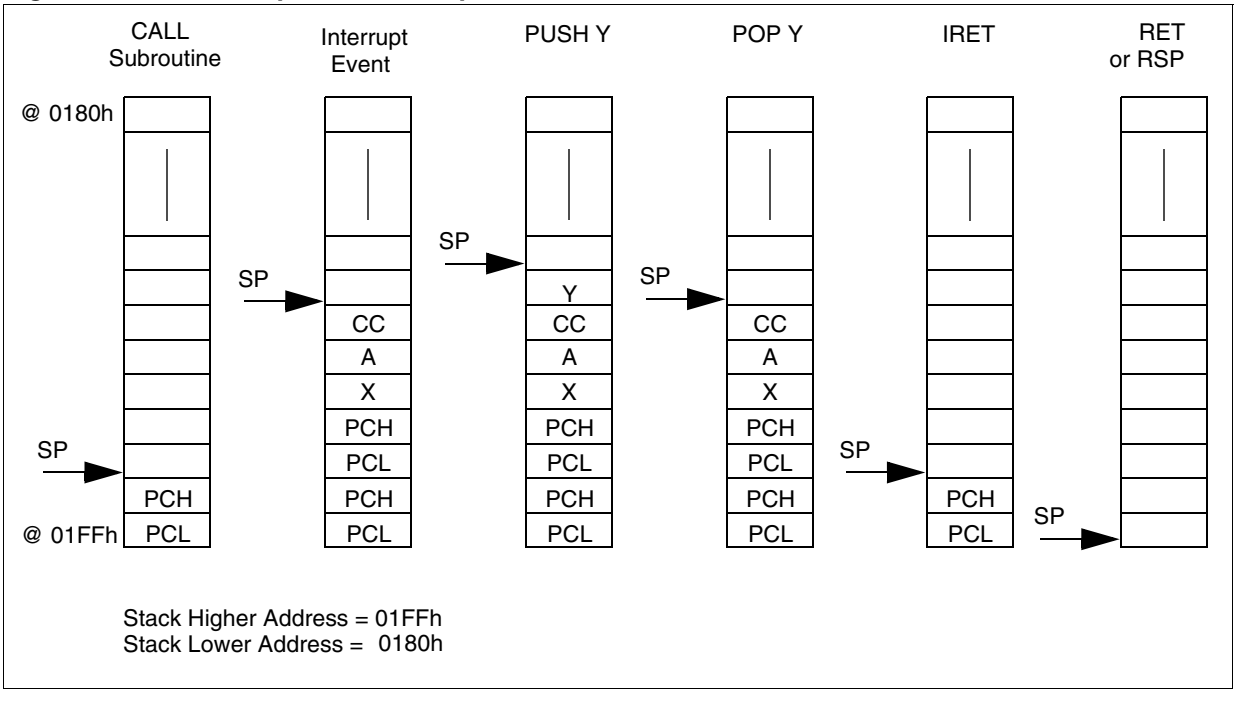
The stack is used to save the return address during a subroutine call and the CPU context during an interrupt. The user may also directly manipulate the stack by means of the PUSH and POP instructions. In the case of an interrupt, the PCL is stored at the first location pointed to by the SP. Then the other registers are stored in the next locations as shown in Figure 12.

– When an interrupt is received, the SP is decremented and the context is pushed on the stack.

– On return from interrupt, the SP is incremented and the context is popped from the stack.

A subroutine call occupies two locations and an interrupt five locations in the stack area.

Figure 12. Stack Manipulation Example



7 SUPPLY, RESET AND CLOCK MANAGEMENT

The device includes a range of utility features for securing the application in critical situations (for example in case of a power brown-out), and reducing the number of external components.

Main features

- Clock Management
  - 1 MHz internal RC oscillator (enabled by option byte, available on ST7LITE15B and ST7LITE19B devices only)
  - 1 to 16 MHz External crystal/ceramic resonator (selected by option byte)
  - External Clock Input (enabled by option byte)
  - PLL for multiplying the frequency by 8 or 4 (enabled by option byte)
  - For clock ART counter only: PLL32 for multiplying the 8 MHz frequency by 4 (enabled by option byte). The 8 MHz input frequency is mandatory and can be obtained in the following ways:
    - –1 MHz RC + PLLx8
    - –16 MHz external clock (internally divided by 2)
    - –2 MHz. external clock (internally divided by 2) + PLLx8
    - –Crystal oscillator with 16 MHz output frequency (internally divided by 2)
- Reset Sequence Manager (RSM)
- System Integrity Management (SI)
  - Main supply Low voltage detection (LVD) with reset generation (enabled by option byte)
  - Auxiliary Voltage detector (AVD) with interrupt capability for monitoring the main supply (enabled by option byte)

7.1 INTERNAL RC OSCILLATOR ADJUSTMENT

The device contains an internal RC oscillator with an accuracy of 1% for a given device, temperature and voltage range (4.5V-5.5V). It must be calibrated to obtain the frequency required in the application. This is done by software writing a 10-bit calibration value in the RCCR (RC Control Register) and in the bits 6:5 in the SICSR (SI Control Status Register).

Whenever the microcontroller is reset, the RCCR returns to its default value (FFh), i.e. each time the device is reset, the calibration value must be loaded in the RCCR. Predefined calibration values are stored in EEPROM for 3 and 5V V_{DD} supply voltages at 25°C, as shown in the following table.

RCCR	Conditions	ST7LITE1xB Address
RCCRH0	V_{DD}=5V T_A=25°C f_{RC}=1MHz	DEE0h [1] (CR[9:2])
RCCRL0		DEE1h [1] (CR[1:0])
RCCRH1	V_{DD}=3.3V T_A=25°C f_{RC}=1MHz	DEE2h [1] (CR[9:2])
RCCRL1		DEE3h [1] (CR[1:0])

1. DEE0h, DEE1h, DEE2h and DEE3h addresses are located in a reserved area of non-volatile memory. They are read-only bytes for the application code. This area cannot be erased or programmed by any ICC operation.

For compatibility reasons with the SICSR register, CR[1:0] bits are stored in the 5th and 6th position of DEE1 and DEE3 addresses.

Notes:

– In 38-pulse ICC mode, the internal RC oscillator is forced as a clock source, regardless of the selection in the option byte. For ST7LITE10B devices which do not support the internal RC oscillator, the “option byte disabled” mode must be used (35-pulse ICC mode entry, clock provided by the tool).

– See “ELECTRICAL CHARACTERISTICS” on page 110. for more information on the frequency and accuracy of the RC oscillator.

– To improve clock stability and frequency accuracy, it is recommended to place a decoupling capacitor, typically 100nF, between the V_{DD} and V_{SS} pins as close as possible to the ST7 device.

– These bytes are systematically programmed by ST, including on FASTROM devices.

Caution: If the voltage or temperature conditions change in the application, the frequency may need to be recalibrated.

Refer to application note AN1324 for information on how to calibrate the RC frequency using an external reference signal.

7.2 PHASE LOCKED LOOP

The PLL can be used to multiply a 1MHz frequency from the RC oscillator or the external clock by 4 or 8 to obtain f_{OSC} of 4 or 8 MHz. The PLL is enabled and the multiplication factor of 4 or 8 is selected by 2 option bits.

– The x4 PLL is intended for operation with V_{DD} in the 2.7V to 3.3V range

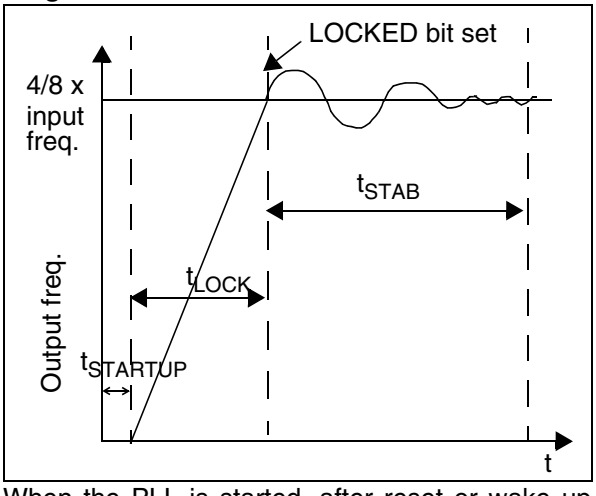
– The x8 PLL is intended for operation with V_{DD} in the 3.3V to 5.5V range [1)]

Refer to Section 15.1 for the option byte description.

If the PLL is disabled and the RC oscillator is enabled, then f_{OSC} = 1MHz.

If both the RC oscillator and the PLL are disabled, f_{OSC} is driven by the external clock.

Figure 13. PLL Output Frequency Timing Diagram



When the PLL is started, after reset or wake up from Halt mode or AWUFH mode, it outputs the clock after a delay of $t_{STARTUP}$.

When the PLL output signal reaches the operating frequency, the LOCKED bit in the SICSCR register is set. Full PLL accuracy (ACC_{PLL}) is reached after a stabilization time of t_{STAB} (see Figure 13 and 13.3.5 Internal RC Oscillator and PLL)

Refer to section 7.6.4 on page 35 for a description of the LOCKED bit in the SICSR register.

Note 1:

It is possible to obtain f_{OSC} = 4MHz in the 3.3V to 5.5V range with internal RC and PLL enabled by selecting 1MHz RC and x8 PLL and setting the PLLdiv2 bit in the PLLTST register (see section 7.6.4 on page 35).

7.3 REGISTER DESCRIPTION

MAIN CLOCK CONTROL/STATUS REGISTER (MCCSR)

Read / Write
Reset Value: 0000 0000 (00h)

7							0
0	0	0	0	0	0	MCO	SMS

Bits 7:2 = Reserved, must be kept cleared.

Bit 1 = **MCO** *Main Clock Out enable*
This bit is read/write by software and cleared by hardware after a reset. This bit allows to enable the MCO output clock.
0: MCO clock disabled, I/O port free for general purpose I/O.
1: MCO clock enabled.

Bit 0 = **SMS** *Slow Mode select*
This bit is read/write by software and cleared by hardware after a reset. This bit selects the input clock f_{OSC} or $f_{OSC}/32$.
0: Normal mode ($f_{CPU} = f_{OSC}$
1: Slow mode ($f_{CPU} = f_{OSC}/32$)

RC CONTROL REGISTER (RCCR)

Read / Write
Reset Value: 1111 1111 (FFh)

7							0
CR9	CR8	CR7	CR6	CR5	CR4	CR3	CR2

Bits 7:0 = **CR[9:2]** *RC Oscillator Frequency Adjustment Bits*
These bits must be written immediately after reset to adjust the RC oscillator frequency and to obtain an accuracy of 1%. The application can store the correct value for each voltage range in EEPROM and write it to this register at start-up.
00h = maximum available frequency
FFh = lowest available frequency
These bits are used with the CR[1:0] bits in the SICSR register. Refer to section 7.6.4 on page 35.

Note: To tune the oscillator, write a series of different values in the register until the correct frequency is reached. The fastest method is to use a dichotomy starting with 80h.